

Growth

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Growth VI: recent views on blue LED efficiency

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1

Growth VI: recent views on blue LED efficiency

- InGaN underlayer
- Surface defects and indium interaction
- Origin of surface defects

2

2

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3

3

■ A look at the blue LED structure



InGaN underlayer (UL):

- Present in all blue LEDs
- Low indium content to limit internal losses
- Either a superlattice or a bulk layer

What is the actual role of the InGaN underlayer?

4

4

InGaN underlayer

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■ Proposed mechanisms

Promote V-pit formation
Zhao *et al.*, Solid State Elec. **54**, 1119 (2010)

Reduction of threading dislocation density
Chen *et al.*, Appl. Phys. Lett. **91**, 081101 (2007)

Less non-radiative centers
Akasaka *et al.*, Appl. Phys. Lett. **85**, 3089 (2004)
Armstrong *et al.*, Appl. Phys. Lett. **117**, 134501 (2015)

Strain mitigation
Nanhui *et al.*, Solid State Elec. **51**, 860 (2007)
Li *et al.*, App. Phys. Lett. **102**, 04115 (2013)
Okada *et al.*, J. Appl. Phys. **117**, 025708 (2015)

Higher injection efficiency
Takahashi *et al.*, Physica E **21**, 876 (2004)
Otsuji *et al.*, J. Appl. Phys. **100**, 113105 (2006)
Ju *et al.*, J. Appl. Phys. **102**, 053519 (2007)
Xia *et al.*, IEEE **57**, 2639 (2010)

Electric field reduction
Davies *et al.*, pss (b) **252**, 866 (2015)
J.-Y. Park *et al.*, pss (a) **213**, 1610 (2016)

Structure: p-type: GaN:Mg / InGaN QWs / InGaN UL / n-type: GaN:Si

MOCVD growth:

Layer	Material
Cap	GaN
SQW	InGaN
Spacer	GaN:Si
UL	InGaN
Buffer	GaN:Si
Substrate	Sapphire/FS GaN

Energy Band Diagram: $E_{\text{laser}} = 375 \text{ nm}$, $E_g(\text{GaN})$, E_v , E_c , $n=2$, $n=1$, $\Delta n=0$, $\Delta n \neq 0$.

5

InGaN underlayer

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■ IQE improvement is independent of the dislocation density

MOCVD growth:

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UL	InGaN
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Substrate	Sapphire/FS GaN

AFM of the surface before InGaN QW growth:

(c) w/o UL, (d) with UL, (e) w/o UL, (f) with UL

300 K photoluminescence resonant pumping at 375 nm:

(b) with InGaN UL, (c) w/o InGaN UL

InGaN UL strongly increases the QW IQE even on GaN substrate

APL **111**, 262101 (2017)

6

InGaN underlayer

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■ Burying GaN surface defects in the InGaN UL

⇒ defect at surface are trapped in the UL and subsequently form NRCs InGaN

C. Haller, ... NG, APL **113**, 111106 (2018)

Structure: HT GaN / Without UL / LT GaN / QW

Indium buries surface defects to form many point defects in QW

7

InGaN underlayer

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■ Cathodoluminescence imaging of point defects

CL Intensity: Integrated intensity, Energy (eV)

CL Image: 25 nm, 1.5 keV

Structure: Al_{0.15}Ga_{0.85}N 5 nm / GaN 10 nm / InGaN QW 3 ML / GaN 25 nm / Underlayer / GaN 1.75 nm / In_{0.15}Al_{0.85}N 2.1 nm / GaN 0.7 μm / GaN Substrate

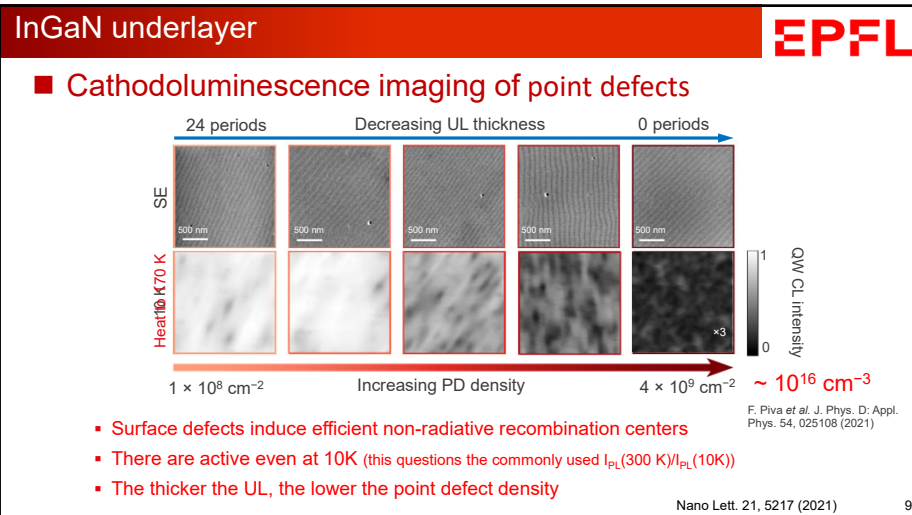
→ Beam energy 1.5 keV

Limit diffusion length → Cryogenic temperature

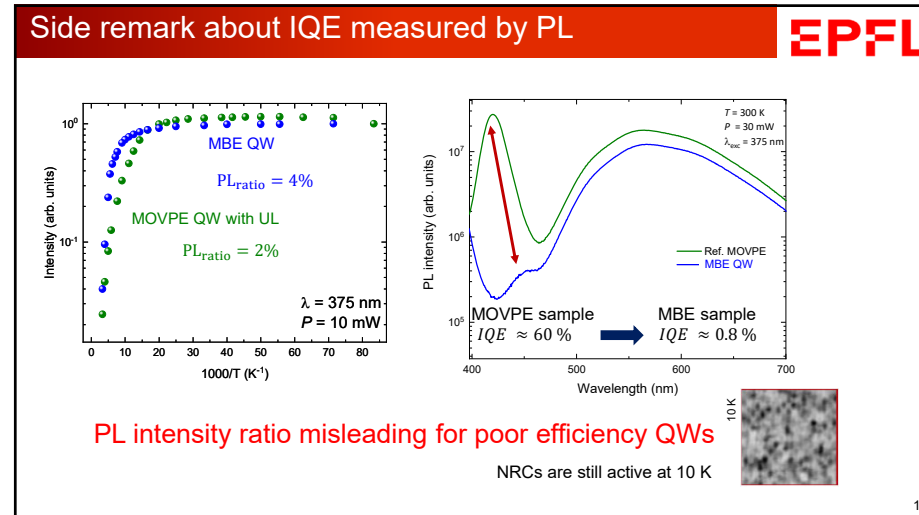
→ 3 ML QW (short radiative lifetime)

Nano Lett. **21**, 5217 (2021)

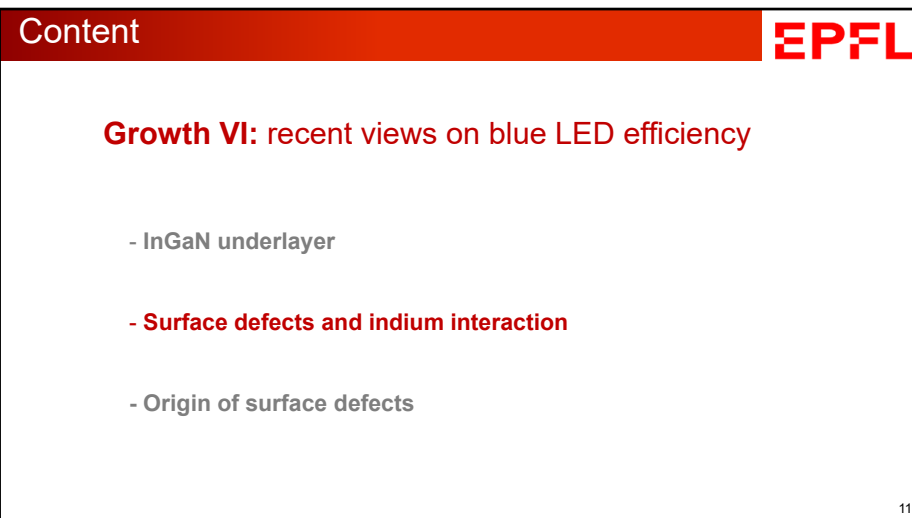
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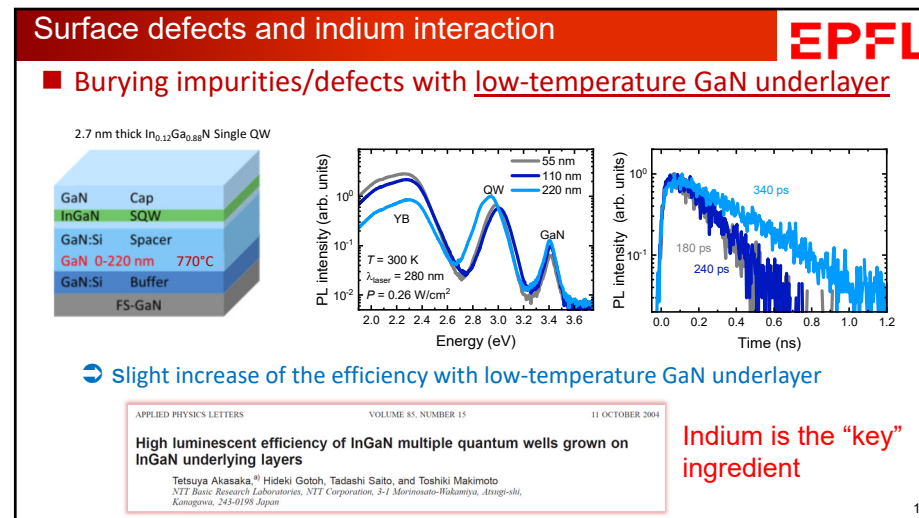
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12

Modeling of the effective lifetime

Hypothesis: the incorporation of a SD in InGaN alloy generates a NRC

$$\frac{1}{\tau_{eff}} = \frac{1}{\tau_0} + \frac{1}{\tau_{NR,SD}} \left\{ \begin{array}{l} \tau_0: \text{lifetime of the QW free of NRCs induced by the SDs} \\ \tau_{NR,SD}: \text{non-radiative lifetime depending on SD incorporation} \end{array} \right.$$

$$\tau_{NR,SD} \propto \frac{1}{[SD]_{QW}} \text{ with } [SD]_{QW} \text{ the concentration of SDs incorporated in the QW}$$

- θ_0 : initial density of SDs after the GaN buffer grown at high-temperature
- SDs segregate at the growth front: $[SD]_{QW} \propto \theta_0 R^N$ K. Muraki et al., APL 61, 557 (1992)
with N the number of deposited monolayers
 R the segregation coefficient (probability to pass from the n^{th} layer to the $n+1^{\text{th}}$ layer)
- SDs are buried when they interact with indium atoms: $R = R_{GaIn} - x\rho$
with R_{GaIn} the segregation coefficient of SDs in GaN
 x the indium composition of the InGaN underlayer
 ρ the interaction efficiency between indium atoms and SDs

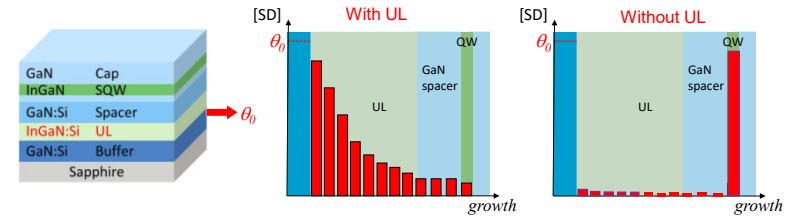
13

Modeling of the effective lifetime

$$\tau_{eff} = \tau_0 \cdot \frac{1}{1 + (\tau_0 \cdot C_{n,p} \cdot C_{QW} \cdot \theta_0 (R_{GaIn} - x \cdot \rho)^N)}$$

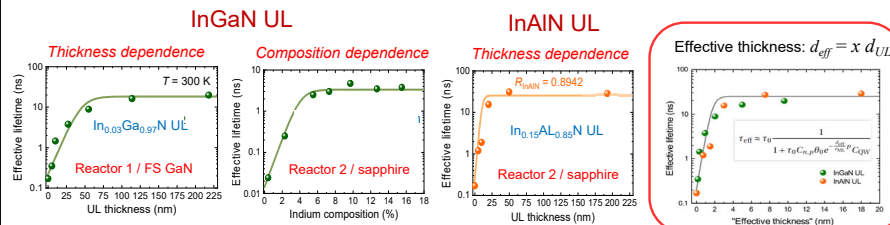
Capture coefficient of SRH centers induced by SD incorporation

Number of SD trapped in the QW: $C_{QW} = (1 - (R_{GaIn} - x_{QW}\rho)^{N_{QW}}) / L_{QW}$



14

Modeling of the effective lifetime



- SD interaction with indium is independent of the material
- Same behavior whatever the MOCVD reactor/substrate
- Strong interaction between indium atoms and SDs

APL 113, 111106 (2018)

15

Consequence for InGaN/GaN MQW properties

APPLIED PHYSICS LETTERS

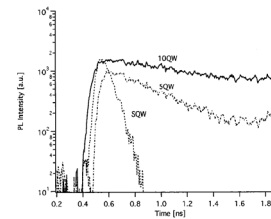
VOLUME 72, NUMBER 9

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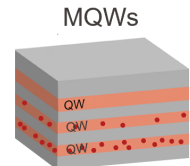
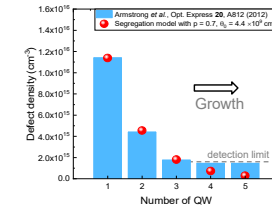
Characterization of high-quality InGaN/GaN multiquantum wells with time-resolved photoluminescence

M. S. Minsky, S. B. Fleischer, A. C. Abare, J. E. Bowers, and E. L. Hu
Department of Electrical and Computer Engineering, University of California, Santa Barbara, California 93106

S. Keller and S. P. Denbaars
Department of Materials, University of California, Santa Barbara, California 93106



Deep level optical spectroscopy on MQWs

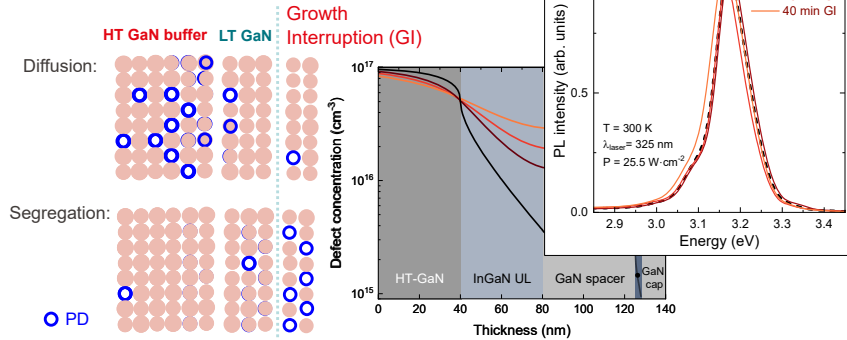


A. Armstrong et al., Opt. Express 20, A812 (2012)

16

■ Segregation or diffusion

- Diffusion happens if a **gradient** exists in the structure
- Surface segregation is a *migration* process toward the surface



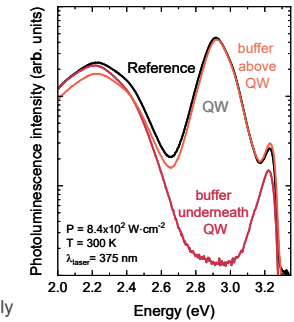
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17

■ Segregation or diffusion

LT GaN spacer 50 nm	LT GaN spacer 50 nm	HT-GaN buffer 300 nm
InGaN 8% QW 3.5 nm	InGaN 8% QW 3.5 nm	LT GaN spacer 50 nm
LT GaN spacer 50 nm	LT GaN spacer 50 nm	InGaN 8% QW 3.5 nm
InGaN 3% UL 150 nm	InGaN 3% UL 150 nm	LT GaN spacer 50 nm
HT-GaN buffer 1 μm	HT-GaN buffer 1 μm	InGaN 3% UL 150 nm
FS GaN	FS GaN	HT-GaN buffer 1 μm
		FS GaN

- HT growth above the QW does not degrade efficiency
→ inline with commercial blue LEDs: p-GaN are commonly grown around 1000 °C
- Strong indication that bulk diffusion of defects is not at play



18

18

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19

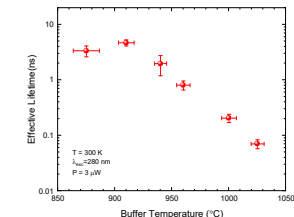
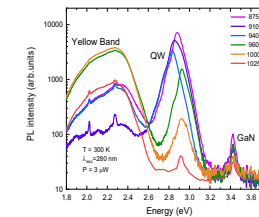
19

■ Impact of the growth temperature

InGaN SQW grown on 1 μm thick GaN buffer on FS-GaN substrate

GaN	755°C	Cap	50 nm
In _{0.12} Ga _{0.88} N	755°C	QW	2.7 nm
GaN	755°C	Barrier	5 nm
GaN	770°C	Spacer	20 nm
GaN	T	Buffer	1 μm
		FS-GaN	

T_{buffer}(°C) = 875, 910, 935, 995, 1050



➡ The HT growth of GaN buffer generates surface defects

Appl. Phys. Lett. 118, 111102 (2021)

20

20

Origin of the surface defects

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What could be these SDs?

Impurities

Li, C, O, Na, Mg, P, K, Ca, Fe, Ti, Cr, Ni, Cu, Zn, Mo (SIMS at EAG Laboratories)

Measured concentration: $[C] = 2 \times 10^{16} \text{ cm}^{-3}$ $[O] = 7 \times 10^{16} \text{ cm}^{-3}$ $[Fe] = 4 \times 10^{14} \text{ cm}^{-3}$ $[Ca] < 2 \times 10^{14} \text{ cm}^{-3}$
Critical concentration: $[C] > 4 \times 10^{17} \text{ cm}^{-3}$ $[O] > 2 \times 10^{17} \text{ cm}^{-3}$ $[Fe] > 1 \times 10^{15} \text{ cm}^{-3}$ $[Ca] > 1 \times 10^{14} \text{ cm}^{-3}$

➔ no correlation between impurities and QW efficiency (detection limit?)

What we learned:

- SDs are created at high temperature ($> 870^\circ\text{C}$)
- SDs strongly segregate in GaN even at low temperature (770°C)
- SDs are independent of the reactor/substrate

➔ SDs could have an intrinsic origin

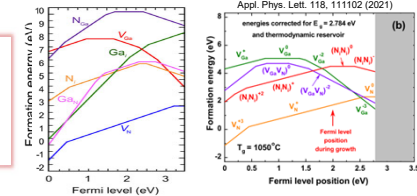
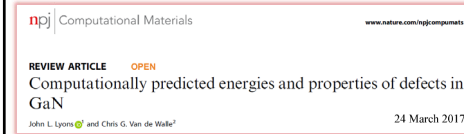
21

21

Origin of the surface defects

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Intrinsic point defects



Surface defect : V_N

- large formation energy and thus unlikely to incorporate in bulk GaN
- form complexes with V_{Ga}
➔ $V_N - V_{Ga}$: major NRCs in n-GaN
S. F. Chichibu et al., JAP 123, 161413 (2018)
- formation energy of V_N lower in InGaN
Obata et al., JCG 311, 2772 (2009)

NRC in InGaN QWs: V_{III}

- large formation energy but V_{Ga} can form complexes with oxygen and/or hydrogen, which are NRCs
C.E. Dreyer et al., APL 108, 141101 (2016)
- V_N are incorporated in InGaN in the form of a $V_N - V_{In}$ complex?

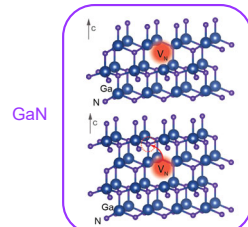
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22

Origin of the surface defects

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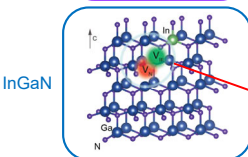
GaN surface defects and NRCs in InGaN alloy



- V_N created during HT GaN growth segregate at the surface
- V_N incorporate into the InGaN QW in the form of $V_{In} - V_N$, due to reduced formation energy

"...the major defect species (in $\text{In}_x\text{Ga}_{1-x}\text{N}$) was identified as complexes between a cation vacancy and a nitrogen vacancy"

Uedono et al., J. Appl. Phys. 113, 123502 (2013)



Major intrinsic NRCs in n-GaN is divacancy composed of $V_N - V_{Ga}$
Chichibu et al., J. Appl. Phys. 123, 161413 (2018)

$V_{In} - V_N$ complex as the main NRC in InGaN QW

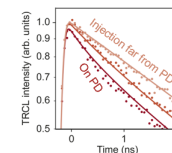
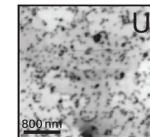
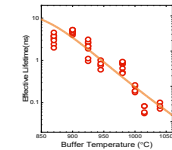
APL Mater. 13, 031111 (2025)

23

23

Summary

- Surface defects (V_N) are generated at HT
They segregate at GaN surface even at LT
- They incorporate in InGaN where they form NRCs
Hypothesis: $V_{In} - V_N$ complex as the main NRC in InGaN QW
- PDs are non-radiative at 10K
Questions the assumption of 100% IQE at LT
- Dislocations are "screened" by V-pits
V-pit sized engineering

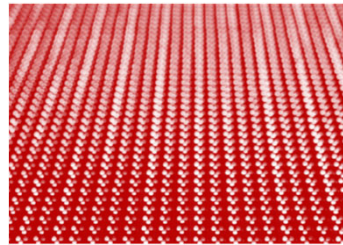


24

24

Are III-nitrides suitable for red LEDs?

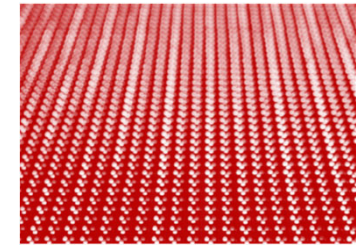
- How to push the wavelength to the red?
- Less strain for more indium



25

Are III-nitrides suitable for red LEDs?

- How to push the wavelength to the red?
- Less strain for more indium

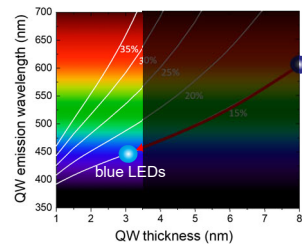


26

How to push the wavelength to the Red ?

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- InGaN/GaN QW emission wavelength

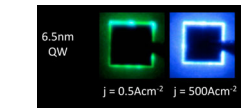
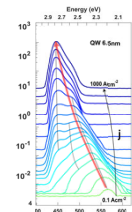


The indium content must be larger than 30%

$$E_{QW} = E_g^{InGaN} + E_{conf}^{e,h} - qL_w F \quad \text{Stark shift}$$

$$x = 15\% \Rightarrow F \approx 1.5 \text{ MV/cm}$$

Red emission (~610 nm) with 15% In and $L_w = 8 \text{ nm}$



Screening of the electric field induces a strong blue-shift

$\Rightarrow L_w$ lower than 4 nm

M. Hajdel *et al.*, Materials **15**, 237 (2022)

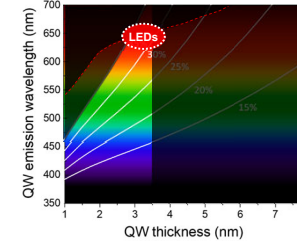
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How to push the wavelength to the Red ?

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- InGaN/GaN QW emission wavelength



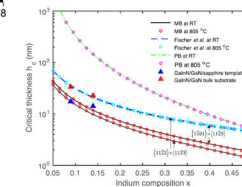
InGaN on GaN critical thickness

G. Ju *et al.*, APL **110**, 262105 (2017)
Amano's group

$$E_{QW} = E_g^{InGaN} + E_{conf}^{e,h} - qL_w F \quad \text{Indium content}$$

« ... less than 35% In composition is normally reported.»

N. Hu *et al.*, APL **121**, 082106 (2022) - Amano's group



The parameter space for red LEDs is quite limited

In content = 30-35%
 $L_w = 3-3.5 \text{ nm}$

28

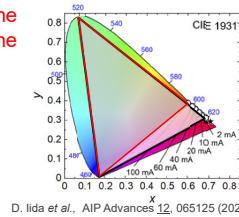
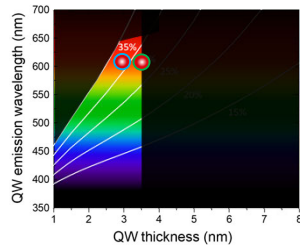
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How to push the wavelength to the Red ?

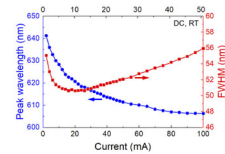
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• Red-LEDs on GaN/sapphire template

At high current density, due to the field screening and band filling, the emission is barely red (610 nm)



The color gamut strongly depends on the "red" wavelength and the FWHM



D. Iida et al., AIP Advances 12, 065125 (2022)

EL peak \neq dominant wavelength

- Extend further the emission wavelength
- Reduce the emission linewidth
- Improve the efficiency

Higher In content \Rightarrow Decrease the strain

29

29

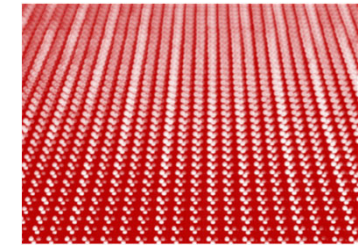
Outline

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Part II: Can we make red LEDs from III-nitrides?

- How to push the wavelength to the red?

- Less strain for more indium



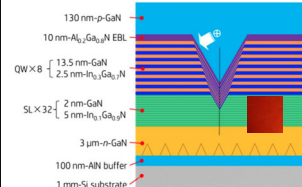
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Less strain for more indium

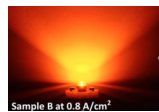
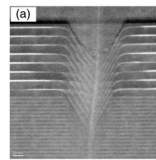
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• Strain relaxation from surface morphology and growth on Si(111)

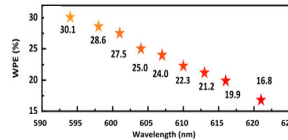


- Growth on silicon \Rightarrow tensile strain
- Large V-pits \Rightarrow strain relaxation
- \Rightarrow Lateral hole injection

F. Jiang et al., Photonics Research 7, 144 (2019) – Nanchang U.



Sample B at 0.8 A/cm²



WPE = 16.8% at 621 nm
Large devices 1x1 mm²

S. Zhang et al., Photonics Research 8, 1671 (2020) Nanchang U.

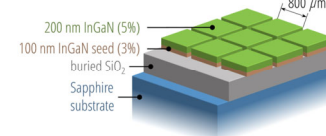
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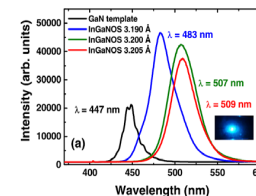
Less strain for more indium

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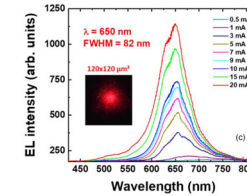
• Pseudo-InGaN substrate (InGaNOS)



- 200nm-thick In_xGa_{1-x}N (x=0.015-0.08) layer on GaN/sapphire
- Transferred using Soitec's Smart Cut™ technology onto a compliant layer
- The InGaN layer is patterned to enable strain relaxation



A. Even et al., APL 110, 262103 (2017) CEA/LETI and Soitec



A. Dussaigne et al., APEX 14, 092011 (2021) CEA/LETI and Soitec

- In content ~40%
- 650 nm with small blueshift
- IQE = 10%
- EQE = 0.14% (with a LEE < 4%)

InGaNOS discontinued

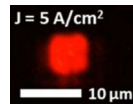
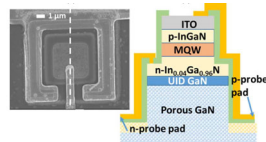
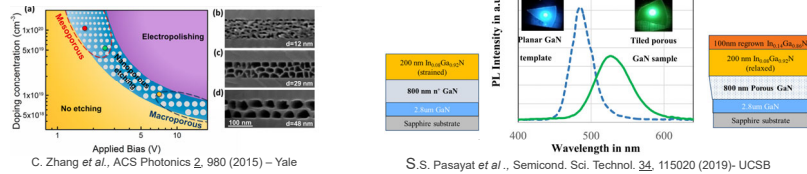
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32

Less strain for more indium

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• Strain relaxation from porous GaN



- 632 nm at 10 A.cm^{-2}
- $6 \mu\text{m} \times 6 \mu\text{m}$ μLEDs
- $\text{EQE} = 0.2\%$

S.S. Pasayat *et al.*, APEX **14**, 011004 (2021) - UCSB

R. Oliver, Cambridge U. and Porotech

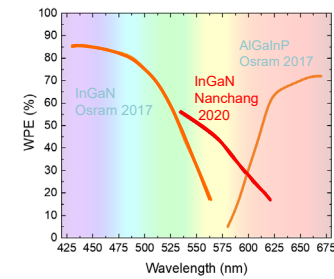
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33

Conclusion

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WPE of InGaN based LEDs – state of the art



InGaN red LEDs

- WPE $\approx 17\%$ at 621 nm
Large devices $1 \times 1 \text{ mm}^2$
Nanchang U.
- WPE $\approx 2\%$ at 630 nm
Small devices $25 \times 25 \mu\text{m}^2$
KAUST + National Taiwan U.

- The green gap is closing
- The III-nitrides may compete for red microLEDs
- InGaN pseudo-substrates are needed

34

34